

## 0.8A, 200V - 1000V Standard Bridge Rectifier

### FEATURES

- AEC-Q101 qualified available
- Ideal for automated placement
- Reliable low cost construction utilizing molded plastic technique
- High surge current capability
- UL Recognized File # E-326854
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

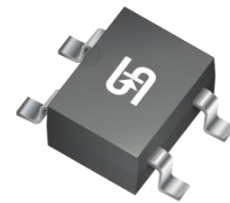
### APPLICATIONS

- Switching mode power supply (SMPS)
- Adapters
- Lighting application

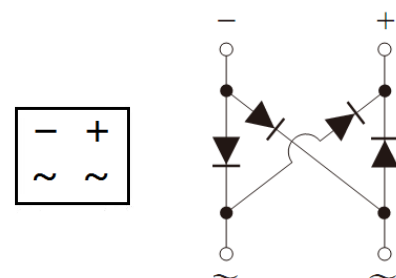
### MECHANICAL DATA

- Case: TO-269AA (MBS)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: As marked
- Weight: 0.120g (approximately)

KEY PARAMETERS		
PARAMETER	VALUE	UNIT
$I_F$	0.8	A
$V_{RRM}$	200 - 1000	V
$I_{FSM}$	35	A
$T_{J\ MAX}$	150	°C
Package	TO-269AA (MBS)	
Configuration	Quad	



MBS



ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)								
PARAMETER	SYMBOL	MBS2	MBS4	MBS6	MBS8	MBS10	UNIT	
Marking code on the device		MBS2	MBS4	MBS6	MBS8	MBS10		
Repetitive peak reverse voltage	$V_{RRM}$	200	400	600	800	1000	V	
Reverse voltage, total rms value	$V_{R(RMS)}$	140	280	420	560	700	V	
Forward current	On glass-epoxy	$I_F$				0.5		A
	On aluminum substrate					0.8		A
Surge peak forward current, 8.3ms single half sine-wave superimposed on rated load	$I_{FSM}$	35				A		
Rating for fusing ( $t < 8.3\text{ms}$ )	$I^2t$	5.08				$\text{A}^2\text{s}$		
Junction temperature	$T_J$	- 55 to +150				°C		
Storage temperature	$T_{STG}$	- 55 to +150				°C		

<b>THERMAL PERFORMANCE</b>			
<b>PARAMETER</b>	<b>SYMBOL</b>	<b>TYP</b>	<b>UNIT</b>
Junction-to-lead thermal resistance <sup>(1)</sup>	$R_{\theta JL}$	20	°C/W
Junction-to-ambient thermal resistance <sup>(2)</sup>	$R_{\theta JA}$	70	°C/W
Junction-to-ambient thermal resistance <sup>(1)</sup>	$R_{\theta JA}$	85	°C/W

**Notes:**

1. On glass epoxy P.C.B. mounted on 0.05" x 0.05" (1.3mm x 1.3mm) pads
2. On aluminum substrate P.C.B. with an area of 0.8" x 0.8" (20mm x 20mm) mounted on 0.05" x 0.05" (1.3mm x 1.3mm) solder pads

<b>ELECTRICAL SPECIFICATIONS</b> ( $T_A = 25^\circ\text{C}$ unless otherwise noted)					
<b>PARAMETER</b>	<b>CONDITIONS</b>	<b>SYMBOL</b>	<b>TYP</b>	<b>MAX</b>	<b>UNIT</b>
Forward voltage per diode <sup>(1)</sup>	$I_F = 0.4\text{A}, T_J = 25^\circ\text{C}$	$V_F$	-	1	V
Reverse current @ rated $V_R$ per diode <sup>(2)</sup>	$T_J = 25^\circ\text{C}$	$I_R$	-	5	$\mu\text{A}$
	$T_J = 125^\circ\text{C}$		-	100	$\mu\text{A}$
Junction capacitance per diode	1MHz, $V_R = 4.0\text{V}$	$C_J$	13	-	pF

**Notes:**

1. Pulse test with PW = 0.3ms
2. Pulse test with PW = 30ms

<b>ORDERING INFORMATION</b>		
<b>ORDERING CODE</b> <sup>(1)(2)</sup>	<b>PACKAGE</b>	<b>PACKING</b>
MBSx	TO-269AA (MBS)	3,000 / Tape & Reel
MBSxH	TO-269AA (MBS)	3,000 / Tape & Reel

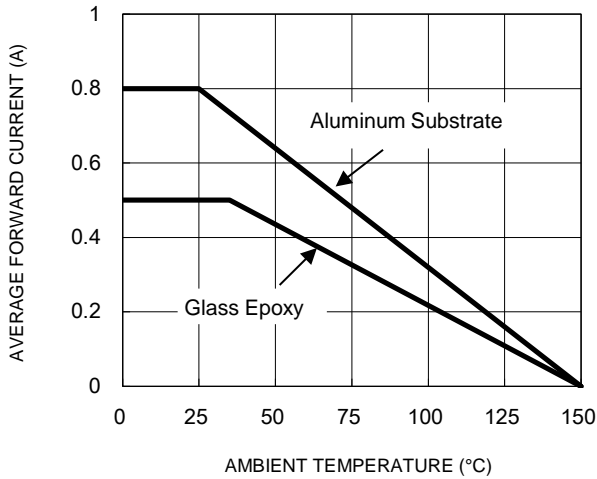
**Notes:**

1. "x" defines voltage from 200V(MBS2) to 1000V(MBS10)
2. "H" means AEC-Q101 qualified

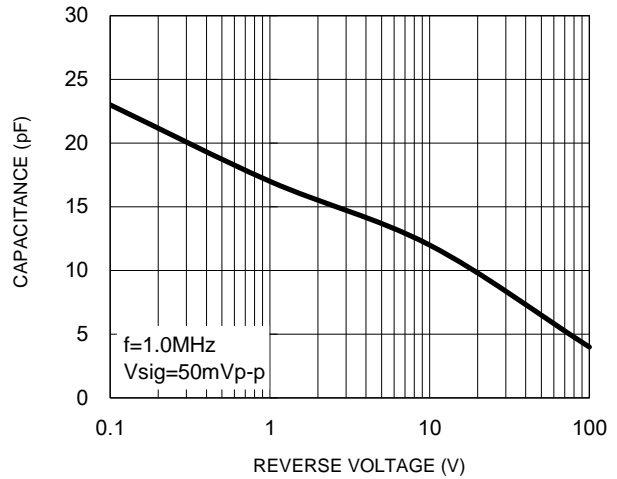
**CHARACTERISTICS CURVES**

( $T_A = 25^\circ\text{C}$  unless otherwise noted)

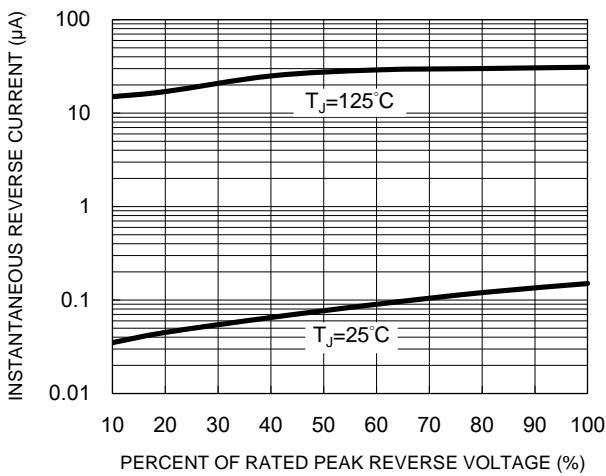
**Fig.1 Forward Current Derating Curve**



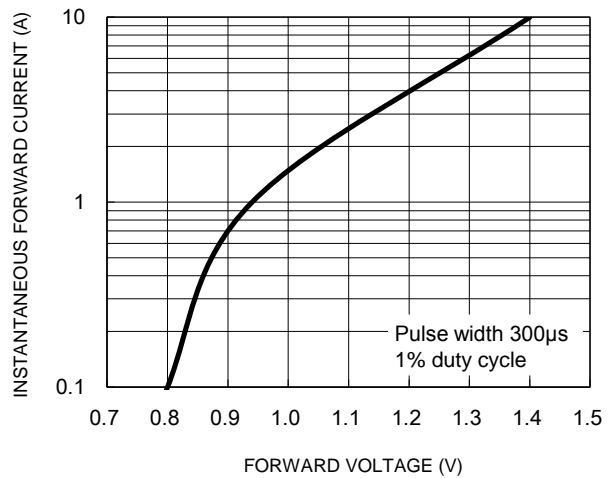
**Fig.2 Typical Junction Capacitance**



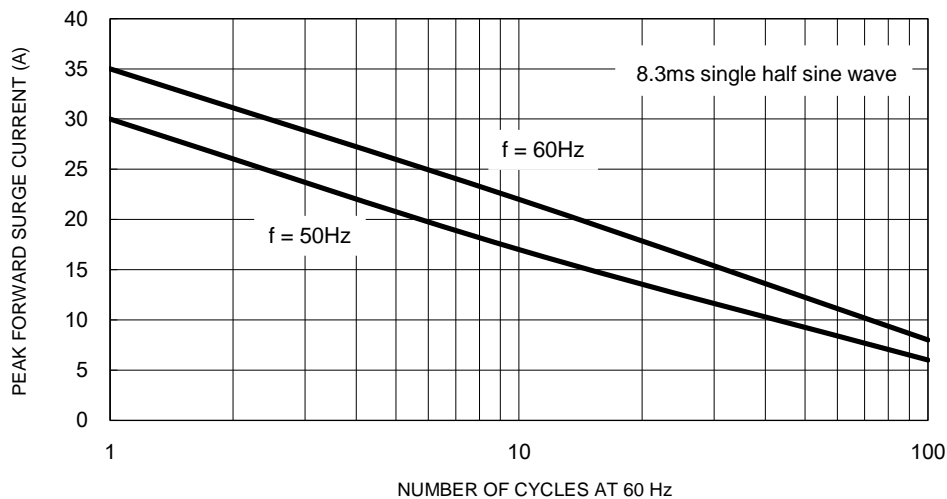
**Fig.3 Typical Reverse Characteristics**



**Fig.4 Typical Forward Characteristics**

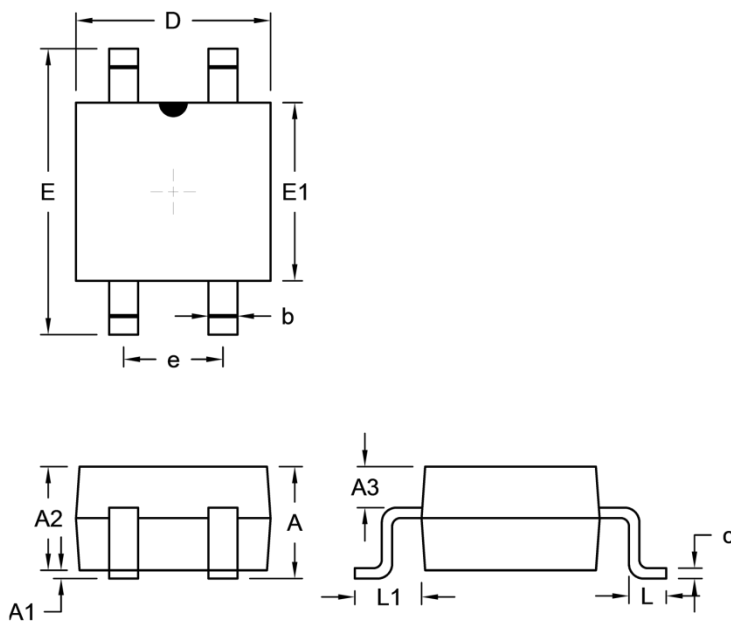


**Fig.5 Maximum Non-Repetitive Forward Surge Current**



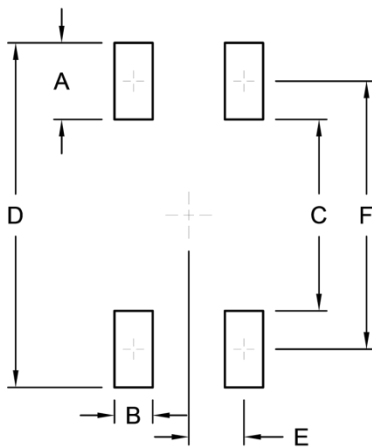
**PACKAGE OUTLINE DIMENSIONS**

TO-269AA (MBS)



DIM.	Unit (mm)		Unit (inch)	
	Min.	Max.	Min.	Max.
A	-	2.90	-	0.114
A1	-	0.20	-	0.008
A2	2.30	2.70	0.091	0.106
A3	0.95	1.53	0.037	0.060
b	0.56	0.84	0.022	0.033
c	0.15	0.35	0.006	0.014
D	4.50	4.90	0.177	0.193
E	-	6.90	-	0.272
E1	3.60	5.00	0.142	0.197
e	2.20	2.60	0.087	0.102
L	0.70	1.10	0.028	0.043
L1	1.10	2.12	0.043	0.083

**SUGGESTED PAD LAYOUT**



Symbol	Unit (mm)	Unit (inch)
A	1.80	0.071
B	0.90	0.035
C	4.50	0.177
D	8.10	0.319
E	1.30	0.051
F	6.30	0.248

**MARKING DIAGRAM**



- P/N = Marking Code
- YW = Date Code
- F = Factory Code